Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NEW PRODUCT

Description

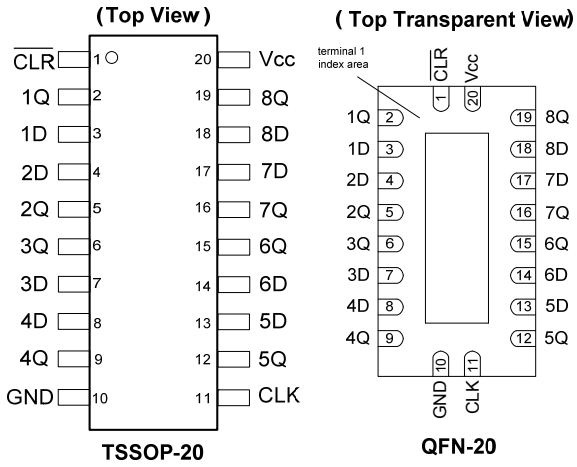
The 74LVC273A provides eight positive-edge-triggered D-type flip-flops with a direct clear (CLR) input.

The device is designed for operation with a power supply range of 1.65V to 3.6V. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

Features

- Supply Voltage Range from 1.65V to 3.6V
- Sinks or Sources 24mA at V_{CC} = 3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial Power Down Operation
- Inputs or Outputs accept up to 5.5V
- Inputs Can Be Driven by 3.3V or 5V Allowing for Mixed Voltage Applications
- Schmitt Trigger Action at All Inputs
- Typical V_{OLP} (Quiet Output Ground Bounce) less than 0.8V with V_{CC} = 3.3V and T_A = +25°C
- Typical V_{OHV} (Quiet Output dynamic VOH) greater than 2.0V with V_{CC} = 3.3V and T_A = +25°C
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115-A)
  - Exceeds 2000-V Human Body Model (A114-A)
  - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 250mA per JESD 78, Class II
- All devices are:
  - **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
  - **Halogen and Antimony Free. "Green" Device (Note 3)**

Pin Assignments



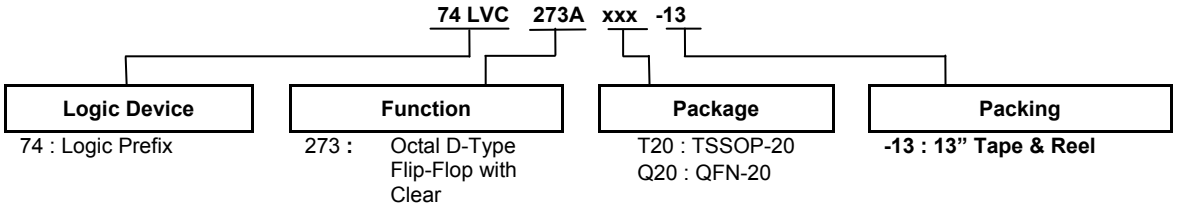
Applications

- General Purpose Logic
- Bus Driving
- Power Down Signal Isolation
- Wide array of products such as:
  - PCs, Notebooks, Netbooks, Ultrabooks
  - Networking Computer Peripherals, Hard Drives, CD/DVD ROM
  - TV, DVD, DVR, Set Top Box

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

NEW PRODUCT

Ordering Information



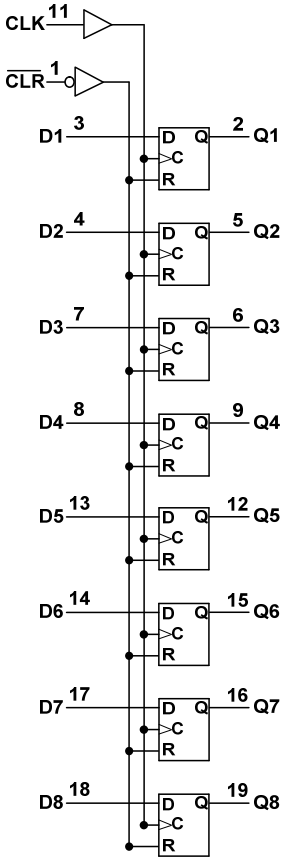
Device	Package Code	Package (Note 4 & 5)	Package Size	13" Tape and Reel	
				Quantity	Part Number Suffix
74LVC273AT20-13	T20	TSSOP-20	6.4mm X 6.5mm X 1.2mm 0.65 mm lead pitch	2500/Tape & Reel	-13
74LVC273AQ20-13	Q20	V-QFN4525-20	2.5mm X 4.5mm X 0.95mm 0.50 mm lead pitch	2500/Tape & Reel	-13

Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
5. V-QFN4525-20 is a JEDEC recognized naming convention that specifies the package thickness category as V and the number 4525 describes the package as 4.5mm X 2.5mm.

Pin Descriptions

Pin Number	Pin Name	Description
1	$\overline{CLR}$	Clear
2	Q1	Latch Output
3	D1	Data Input
4	D2	Data Input
5	Q2	Latch Output
6	Q3	Latch Output
7	D3	Data Input
8	D4	Data Input
9	Q4	Latch Output
10	GND	Ground
11	CLK	Clock
12	Q5	Latch Output
13	D5	Data Input
14	D6	Data Input
15	Q6	Latch Output
16	Q7	Latch Output
17	D7	Data Input
18	D8	Data Input
19	Q8	Latch Output
20	Vcc	Supply Voltage

Logic Diagram



Function Table

(Each Flip-Flop)			
INPUTS			OUTPUT
$\overline{CLR}$	CLK	D	Q
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q_0

NEW PRODUCT

Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +7.0	V
V_I	Input Voltage Range	-0.5 to +7.0	V
I_{IK}	Input Clamp Current V_I< 0V	-20	mA
I_{OK}	Output Clamp Current V_O< 0V	-50	mA
I_O	Continuous output current -0.5V < V_O V_{cc} +0.5V	±50	mA
I_{CC}	Continuous Current Through V_{cc}	100	mA
I_{GND}	Continuous Current Through GND	-100	mA
T_J	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature	-65 to +150	°C
P_{TOT}	Total Power Dissipation	500	mW

Notes: 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage	Operating	1.65	3.6	V
		Data Retention Only	1.5	—	V
V_I	Input Voltage	—	0	5.5	V
V_O	Output Voltage	—	0	V_{CC}	V
I_{OH}	High-Level Output Current	V_{CC} = 1.65V	—	-4	mA
		V_{CC} = 2.3V	—	-8	
		V_{CC} = 2.7V	—	-12	
		V_{CC} = 3.0V	—	-24	
I_{OL}	Low-Level Output Current	V_{CC} = 1.65V	—	4	mA
		V_{CC} = 2.3V	—	8	
		V_{CC} = 2.7V	—	12	
		V_{CC} = 3.0V	—	24	
Δt/ΔV	Input Transition Rise or Fall Rate		—	10	ns/V
T_A	Operating Free-Air Temperature		-40	+125	°C

Note: 8. Unused inputs should be held at V_{CC} or ground.

NEW PRODUCT

Electrical Characteristics

Symbol	Parameter	Test Conditions		V_{CC}	T_A = -40°C to +85°C		T_A = +85°C to +125°C		Unit
					Min	Max	Min	Max	
V_{IH}	High-Level Input Voltage			1.65V to 1.95V	V_{CC} X 0.65		V_{CC} X 0.65		V
				2.3V to 2.7V	1.7		1.7		
				3.0V to 3.6V	2		2		
V_{IL}	Low-Level Input voltage			1.65V to 1.95V		V_{CC} X 0.35		V_{CC} X 0.35	V
				2.3V to 2.7V		0.7		0.7	
				3.0V to 3.6V		0.8		0.8	
V_{OH}	High-Level Output Voltage	I_{OH} = -50µA		1.65V to 3.6V	V_{CC} -0.2		V_{CC}-0.3		
		I_{OH} = -4mA		1.65V	1.2		1.05		
		I_{OH} = -8mA		2.3V	1.7		1.65		V
		I_{OH} = -12mA		2.7V	2.2		2.05		
				3.0V	2.4		2.48		
		I_{OH} = -24mA		3.0V	2.3		2.0		
V_{OL}	Low-Level Output Voltage	I_{OL} = 100µA		1.65V to 3.6V		0.2		0.3	V
		I_{OL} = 4mA		1.65V		0.45		0.65	
		I_{OL} = 8mA		2.3V		0.60		0.80	
		I_{OL} = 12mA		2.7V		0.40		0.60	
		I_{OL} = 24mA		3.0V		0.55		0.80	
I_{OFF}	Power Down Leakage Current	V_I or V_O = 0 or 5.5V		0V		±10		20	µA
I_I	Input Current Control Pins	V_I = GND or 5.5V		0 to 3.6V		±5		± 20	µA
I_{CC}	Supply Current	V_I = GND or V_{CC}, I_O = 0		6.0V		10		40	µA
ΔI_{CC}	Additional Supply Current	One input at Vcc-0.6V Io = 0A		2.7V to 3.6V		500		5000	µA
C_i	Input Capacitance	Control Pins	V_I = GND or V_{CC}	0V to 3.6V	4.0 typical		4.0 typical		pF
		I/O Pins			5.5 typical		5.5 typical		

NEW PRODUCT

Switching Characteristics

Symbol	Parameter	Test Conditions	V_{CC}	T_A = +25°C			-40°C to +85°C		+85°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
f_{MAX}	Maximum Frequency	Figure 1	1.8V ± 0.15V	35	40		35		30		Mhz
			2.5V ± 0.3V	75	60		50		45		
			2.7V	150	175		150		100		
			3.3V ± 0.3	150	230		150		125		
t_W	Pulse Width CLK High or Low	Figure 1	1.8V ± 0.15V	5.0	2.5		5.0		5.5		ns
			2.5V ± 0.3V	4.0	2.0		4.0		4.5		
			2.7V	3.3	1.7		3.3		3.5		
			3.3V ± 0.3V	3.0	1.5		3.0		3.5		
t_W	Pulse Width $\overline{CLR}$ Low	Figure 1	1.8V ± 0.15V	5.0	2.5		5.0		5.5		ns
			2.5V ± 0.3V	4.0	2.0		4.0		4.5		
			2.7V	3.3	1.7		3.3		3.5		
			3.3V ± 0.3V	3.0	1.5		3.0		3.5		
t_{SU}	Set-up Time D_N to CLK	Figure 1	1.8V ± 0.15V	4.0	2.0		4.0		4.5	t_{SU}	ns
			2.5V ± 0.3V	3.0	1.5		3.0		3.5		
			2.7V	2.0	1.0		2.0		2.5		
			3.3V ± 0.3V	1.5	1.0		1.5		2.0		
t_H	Hold Time D_N to CLK	Figure 1	1.8V ± 0.15V	3.0	1.5		3.0		3.5		ns
			2.5V ± 0.3V	2.0	1.0		2.0		2.5		
			2.7V	1.5	1.0		1.5		2.0		
			3.3V ± 0.3V	1.5	1.0		1.5		2.0		
t_{REM}	Removal Time $\overline{CLR}$ to CLK	Figure 1	1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2	ns
			2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	
			2.7V	1	4.4	8.3	1	8.5	1	10.0	
			3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0	
t_{PD}	Propagation Delay CLK to Q_N	Figure 1	1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2	ns
			2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	
			2.7V	1	4.4	8.3	1	8.5	1	10.0	
			3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0	
t_{PD}	Propagation Delay $\overline{CLR}$ to Q_N	Figure 1	1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2	ns
			2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	
			2.7V	1	4.4	8.3	1	8.5	1	10.0	
			3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0	
tsk(0)	Output Skew Time		3.3V ± 0.3V			1.0				1.5	ns

Operating Characteristics

T_A = +25°C

Symbol	Parameter	Test Conditions	V_{CC}	TYP	Unit
C_{pd}	Power dissipation capacitance per gate	F = 10 MHz	1.8V ± 0.15V	9.9	pF
			2.5V ± 0.3V	10.2	
			3.3V ± 0.3V	10.6	

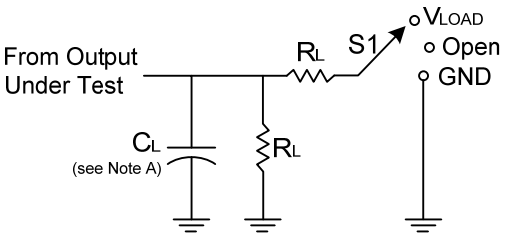
Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Typ	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	TSSOP-20	(Note 9)	—	74	—	°C/W
θ_{JC}	Thermal Resistance Junction-to-Case	TSSOP-20	(Note 9)	—	15	—	°C/W
θ_{JA}	Thermal Resistance Junction-to-Ambient	V-QFN4525-20	(Note 9)	—	67	—	°C/W
θ_{JC}	Thermal Resistance Junction-to-Case	V-QFN4525-20	(Note 9)	—	20	—	°C/W

Note: 9. Test conditions for TSSOP-20 and V-QFN4525-20: Devices mounted on 4 layer FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout per JESD 51-7.

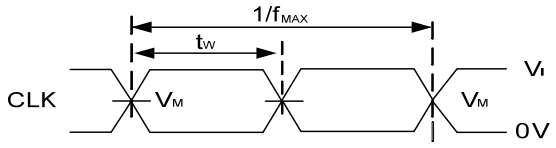
NEW PRODUCT

Parameter Measurement Information

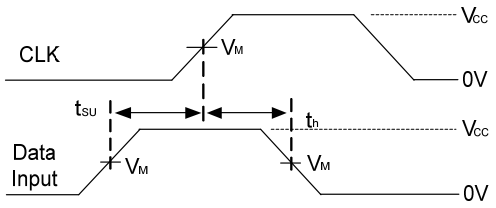


TEST	S1
t_{PLH}/t_{PHL}	Open

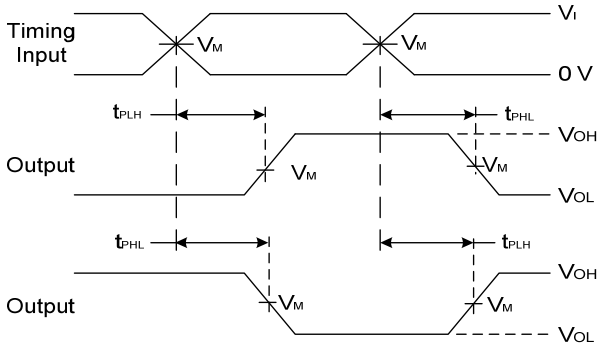
V_{CC}	Inputs		V_M	V_{LOAD}	C_L	R_L	$V\Delta$
	V_I	t_r/t_f					
1.8V ± 0.15V	V_{CC}	≤2ns	$V_{CC}/2$	2 x V_{CC}	30pF	1KΩ	0.15V
2.5V ± 0.2V	V_{CC}	≤2ns	$V_{CC}/2$	2 x V_{CC}	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V ± 0.3V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V



Voltage Waveform Pulse Duration



Voltage Waveform Set-up and Hold Times



Voltage Waveform Propagation Delay Times
Inverting and Non Inverting Outputs

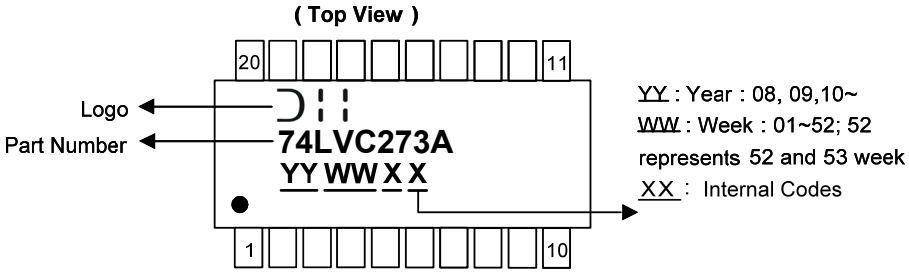
Notes:
A. Includes test lead and test apparatus capacitance.
B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
C. Inputs are measured separately one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Figure 1 Load Circuit and Voltage Waveforms

NEW PRODUCT

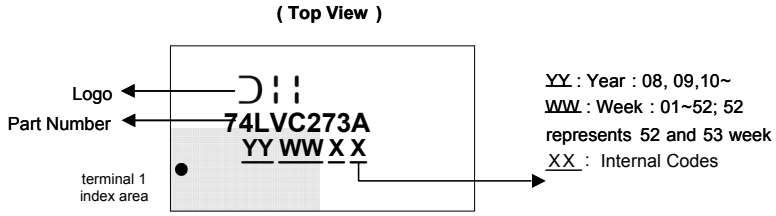
Marking Information

(1) TSSOP20



Part Number	Package
74LVC273AT20	TSSOP-20

(2) QFN-20 (V-QFN4525-20)



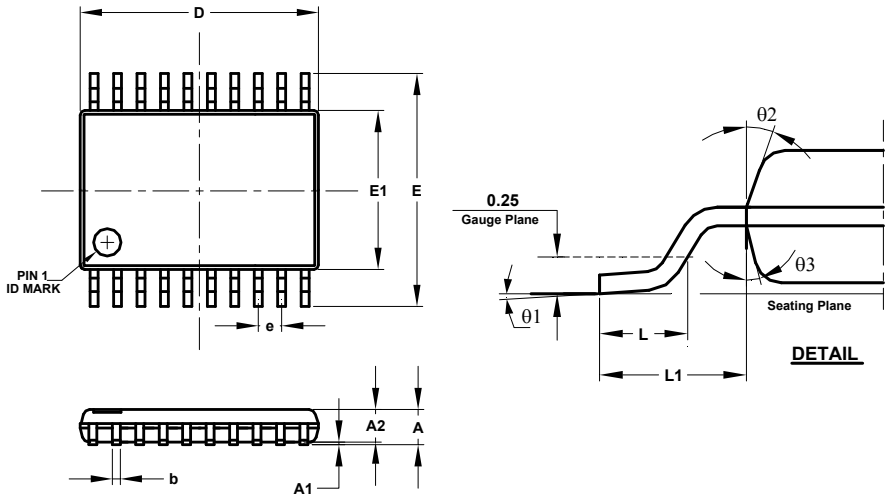
Part Number	Package
74LVC273AQ20	V-QFN4525-20

NEW PRODUCT

Package Outline Dimensions (All Dimensions in mm)

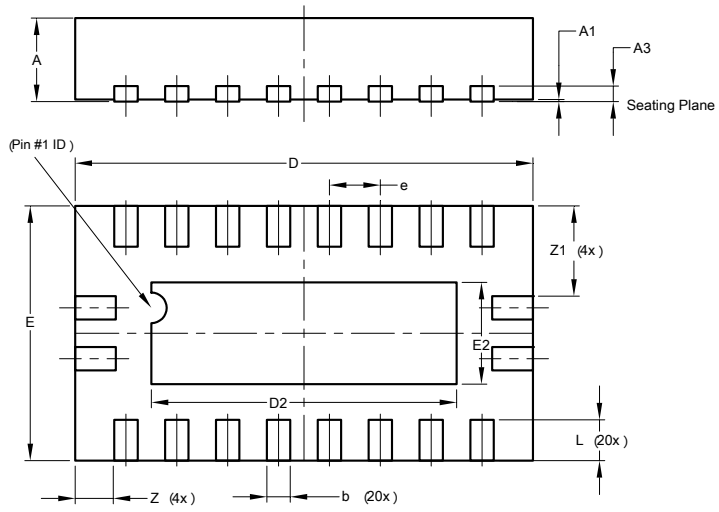
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

(1) TSSOP-20



TSSOP-20			
Dim	Min	Max	Typ
A	-	1.20	-
A1	0.05	0.15	-
A2	0.80	1.05	-
b	0.19	0.30	-
c	0.09	0.20	-
D	6.40	6.60	6.50
E	6.20	6.60	6.40
E1	4.30	4.50	4.40
e	0.65 BSC		
L	0.45	0.75	0.60
L1	1.0 REF		
θ1	0°	8°	-
θ2	10°	14°	12°
θ3	10°	14°	12°
All Dimensions in mm			

(2) QFN-20 (V-QFN4525-20)



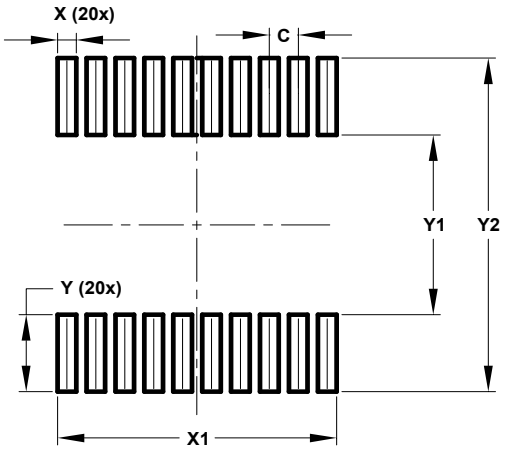
V-QFN4525-20			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	-	-	0.15
b	0.18	0.30	0.23
D	4.45	4.55	4.50
D2	2.85	3.15	3.00
E	2.45	2.55	2.50
E2	0.85	1.15	1.00
e	0.50BSC		
L	0.30	0.50	0.40
Z	-	-	0.385
Z1	-	-	0.885
All Dimensions in mm			

NEW PRODUCT

Suggested Pad Layout

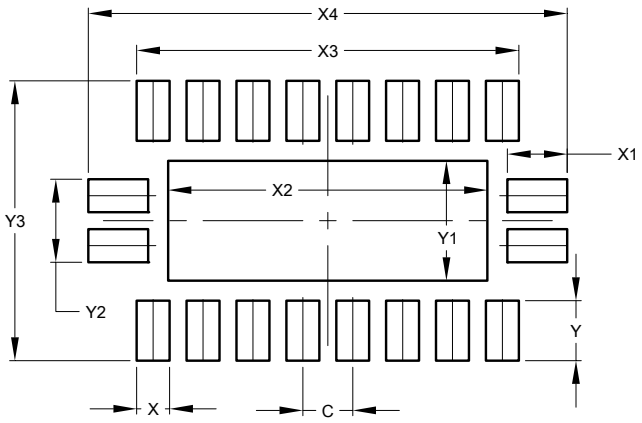
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

(1) TSSOP-20



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	6.270
Y	1.789
Y1	4.160
Y2	7.720

(2) QFN-20 (V-QFN4525-20)



Dimensions	Value (in mm)
C	0.500
X	0.330
X1	0.600
X2	3.200
X3	3.830
X4	4.800
Y	0.600
Y1	1.200
Y2	0.830
Y3	2.800

NEW PRODUCT

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

www.diodes.com